

IGBT – Power, Co-PAK

**N-Channel, Field Stop VII (FS7),
SCR, Power TO247-3L,
1200 V, 1.4 V, 100 A**

FGY100T120RWD

Description

Using the novel field stop 7th generation IGBT technology and the Gen7 Diode in TP247 3-lead package, FGY100T120RWD offers the optimum performance with low conduction losses and good switching controllability for a high efficiency operation in various applications like motor control, UPS, data center and high-power switch.

Features

- Low Conduction Loss and Optimized Switching
- Maximum Junction Temperature – $T_J = 175^{\circ}\text{C}$
- Positive Temperature Coefficient for Easy Parallel Operation
- High Current Capability
- 100% of the Parts are Dynamically Tested
- Short Circuit Rated
- RoHS Compliant

Applications

- Motor Control
- UPS
- General Application Requiring High Power Switch

MAXIMUM RATINGS ($T_J = 25^{\circ}\text{C}$ unless otherwise noted)

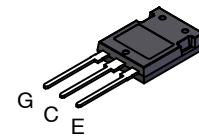
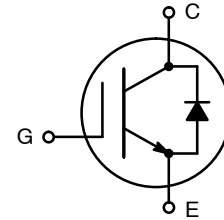
Parameter	Symbol	Value	Unit
Collector to Emitter Voltage	V_{CES}	1200	V
Gate to Emitter Voltage	V_{GES}	± 20	
Transient Gate to Emitter Voltage		± 30	
Collector Current	I_C	$T_C = 25^{\circ}\text{C}$	A
		$T_C = 100^{\circ}\text{C}$	
Power Dissipation	P_D	$T_C = 25^{\circ}\text{C}$	W
		$T_C = 100^{\circ}\text{C}$	
Pulsed Collector Current	I_{CM}	300	A
Diode Forward Current	I_F	$T_C = 25^{\circ}\text{C}$	200
		$T_C = 100^{\circ}\text{C}$	
Pulsed Diode Forward Current	I_{FM}	300	
Short Circuit Withstand Time $V_{GE} = 15\text{ V}, V_{CC} = 600\text{ V}, T_C = 150^{\circ}\text{C}$	T_{SC}	5	μs
Operating Junction and Storage Temperature	T_J, T_{STG}	-55 to 175	$^{\circ}\text{C}$
Lead Temperature for Soldering Purposes	T_L	260	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse width limited by max. Junction temperature.

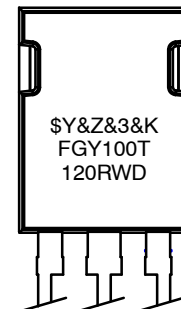
BV_{CES}	$V_{CE(SAT)}$	I_C
1200 V	1.4 V	100 A

PIN CONNECTIONS



TO247-3LD
CASE 340CD

MARKING DIAGRAM



$\$Y$ = onsemi logo
 $\&Z$ = Assembly Plant Code
 $\&3$ = 3-Digit Date Code
 $\&K$ = 2-Digit Lot Traceability Code
 FGY100T120RWD = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping
FGY100T120RWD	TO247-3LD (Pb-Free)	30 Units / Tube

FGY100T120RWD

THERMAL CHARACTERISTICS

Parameter	Symbol	Max Value	Unit
Thermal Resistance, Junction to Case for IGBT	$R_{\theta JC}$	0.1	$^{\circ}\text{C/W}$
Thermal Resistance, Junction to Case for Diode		0.19	
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	40	

ELECTRICAL CHARACTERISTICS OF THE IGBT ($T_J = 25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Collector to Emitter Breakdown Voltage	BV_{CES}	$V_{GE} = 0\text{ V}, I_C = 5\text{ mA}$	1200	–	–	V
Breakdown Voltage Temperature Coefficient	$\Delta BV_{CES} / \Delta T_J$	$V_{GE} = 0\text{ V}, I_C = 5\text{ mA}$	–	662	–	$\text{mV}/^{\circ}\text{C}$
Collector to Emitter Cut-Off Current	I_{CES}	$V_{GE} = 0\text{ V}, V_{CE} = V_{CES}$	–	–	40	μA
Gate to Emitter Leakage Current	I_{GES}	$V_{GE} = 20\text{ V}, V_{CE} = 0\text{ V}$	–	–	± 400	nA

ON CHARACTERISTICS

Gate to Emitter Threshold Voltage	$V_{GE(TH)}$	$V_{GE} = V_{CE}, I_C = 100\text{ mA}$	4.9	5.92	6.7	V
Collector to Emitter Saturation Voltage	$V_{CE(SAT)}$	$V_{GE} = 15\text{ V}, I_C = 100\text{ A}, T_J = 25^{\circ}\text{C}$	–	1.43	–	V
		$V_{GE} = 15\text{ V}, I_C = 100\text{ A}, T_J = 175^{\circ}\text{C}$	–	1.66	–	

DYNAMIC CHARACTERISTICS

Input Capacitance	C_{IES}	$V_{CE} = 30\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$	–	12200	–	pF
Output Capacitance	C_{OES}		–	392	–	
Reverse Transfer Capacitance	C_{RES}		–	44.2	–	
Total Gate Charge	Q_G	$V_{CE} = 600\text{ V}, V_{GE} = 15\text{ V}, I_C = 100\text{ A}$	–	427	–	nC
Gate to Emitter Charge	Q_{GE}		–	108	–	
Gate to Collector Charge	Q_{GC}		–	161	–	

SWITCHING CHARACTERISTIC, INDUCTIVE LOAD

Turn-On Delay Time	$t_{d(on)}$	$V_{CE} = 600\text{ V}, V_{GE} = 15\text{ V}, I_C = 50\text{ A}, R_G = 4.7\ \Omega, T_J = 25^{\circ}\text{C}$	–	74	–	ns
Turn-Off Delay Time	$t_{d(off)}$		–	464	–	ns
Rise Time	t_r		–	45	–	ns
Fall Time	t_f		–	196	–	
Turn-On Switching Loss	E_{on}		–	3.43	–	mJ
Turn-Off Switching Loss	E_{off}		–	4.54	–	
Total Switching Loss	E_{ts}		–	7.97	–	
Turn-On Delay Time	$t_{d(on)}$	$V_{CE} = 600\text{ V}, V_{GE} = 15\text{ V}, I_C = 100\text{ A}, R_G = 4.7\ \Omega, T_J = 25^{\circ}\text{C}$	–	80	–	ns
Turn-Off Delay Time	$t_{d(off)}$		–	364	–	ns
Rise Time	t_r		–	85	–	ns
Fall Time	t_f		–	180	–	
Turn-On Switching Loss	E_{on}		–	8.13	–	mJ
Turn-Off Switching Loss	E_{off}		–	7.05	–	
Total Switching Loss	E_{ts}		–	15.18	–	

FGY100T120RWD

ELECTRICAL CHARACTERISTICS OF THE IGBT ($T_J = 25^\circ\text{C}$ unless otherwise noted) (continued)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
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SWITCHING CHARACTERISTIC, INDUCTIVE LOAD

Turn-On Delay Time	$t_{d(on)}$	$V_{CE} = 600\text{ V}, V_{GE} = 15\text{ V},$ $I_C = 50\text{ A}, R_G = 4.7\ \Omega,$ $T_J = 175^\circ\text{C}$	–	70	–	ns
Turn-Off Delay Time	$t_{d(off)}$		–	536	–	ns
Rise Time	t_r		–	50	–	ns
Fall Time	t_f		–	348	–	
Turn-On Switching Loss	E_{on}		–	5.58	–	mJ
Turn-Off Switching Loss	E_{off}		–	6.83	–	
Total Switching Loss	E_{ts}		–	12.41	–	
Turn-On Delay Time	$t_{d(on)}$	$V_{CE} = 600\text{ V}, V_{GE} = 15\text{ V},$ $I_C = 100\text{ A}, R_G = 4.7\ \Omega,$ $T_J = 175^\circ\text{C}$	–	78	–	ns
Turn-Off Delay Time	$t_{d(off)}$		–	412	–	ns
Rise Time	t_r		–	93	–	ns
Fall Time	t_f		–	316	–	
Turn-On Switching Loss	E_{on}		–	12.00	–	mJ
Turn-Off Switching Loss	E_{off}		–	10.30	–	
Total Switching Loss	E_{ts}		–	22.30	–	

DIODE CHARACTERISTIC

Diode Forward Voltage	V_F	$I_F = 100\text{ A}, T_J = 25^\circ\text{C}$	–	1.80	–	V
		$I_F = 100\text{ A}, T_J = 175^\circ\text{C}$	–	1.90	–	

DIODE SWITCHING CHARACTERISTIC, INDUCTIVE LOAD

Reverse Recovery Time	t_{rr}	$V_R = 600\text{ V}, I_F = 50\text{ A},$ $di_F/dt = 500\text{ A}/\mu\text{s},$ $T_J = 25^\circ\text{C}$	–	256	–	ns
Reverse Recovery Charge	Q_{rr}		–	3140	–	nC
Reverse Recovery Energy	E_{rec}		–	1	–	mJ
Peak Reverse Recovery Current	I_{RRM}		–	24.5	–	A
Reverse Recovery Time	t_{rr}	$V_R = 600\text{ V}, I_F = 100\text{ A},$ $di_F/dt = 500\text{ A}/\mu\text{s},$ $T_J = 25^\circ\text{C}$	–	347	–	ns
Reverse Recovery Charge	Q_{rr}		–	4408	–	nC
Reverse Recovery Energy	E_{rec}		–	2	–	mJ
Peak Reverse Recovery Current	I_{RRM}		–	25.8	–	A
Reverse Recovery Time	t_{rr}	$V_R = 600\text{ V}, I_F = 50\text{ A},$ $di_F/dt = 500\text{ A}/\mu\text{s},$ $T_J = 175^\circ\text{C}$	–	424	–	ns
Reverse Recovery Charge	Q_{rr}		–	8610	–	nC
Reverse Recovery Energy	E_{rec}		–	4	–	mJ
Peak Reverse Recovery Current	I_{RRM}		–	40.8	–	A
Reverse Recovery Time	t_{rr}	$V_R = 600\text{ V}, I_F = 100\text{ A},$ $di_F/dt = 500\text{ A}/\mu\text{s},$ $T_J = 175^\circ\text{C}$	–	572	–	ns
Reverse Recovery Charge	Q_{rr}		–	12476	–	nC
Reverse Recovery Energy	E_{rec}		–	5	–	mJ
Peak Reverse Recovery Current	I_{RRM}		–	43.6	–	A

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

FGY100T120RWD

TYPICAL CHARACTERISTICS

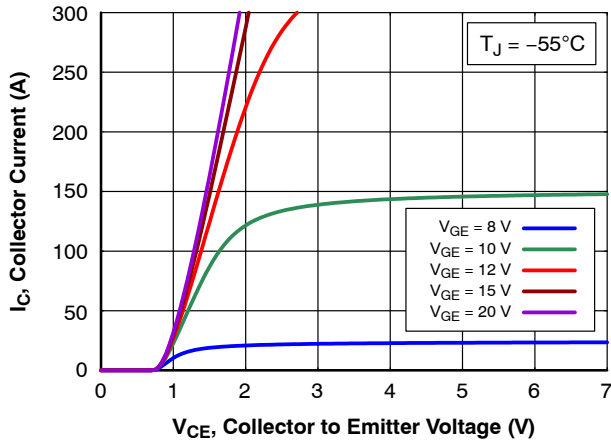


Figure 1. Output Characteristics

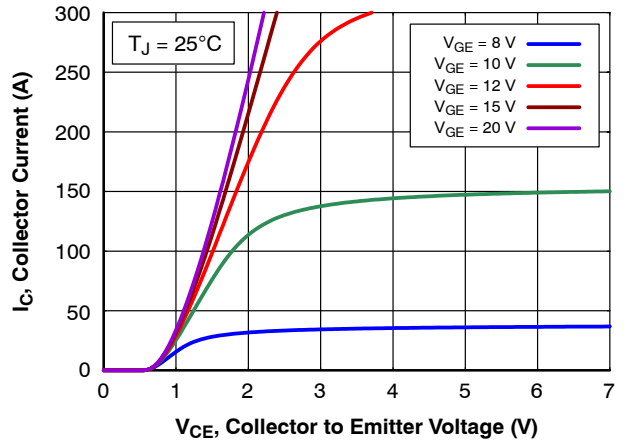


Figure 2. Output Characteristics

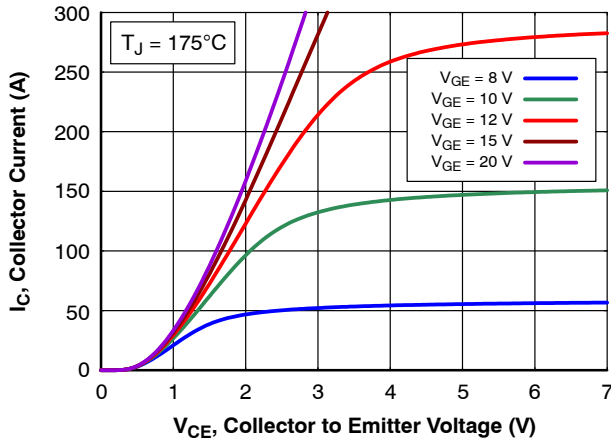


Figure 3. Output Characteristics

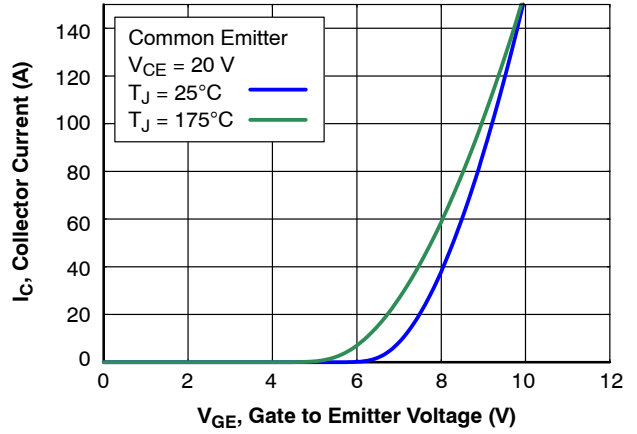


Figure 4. Transfer Characteristics

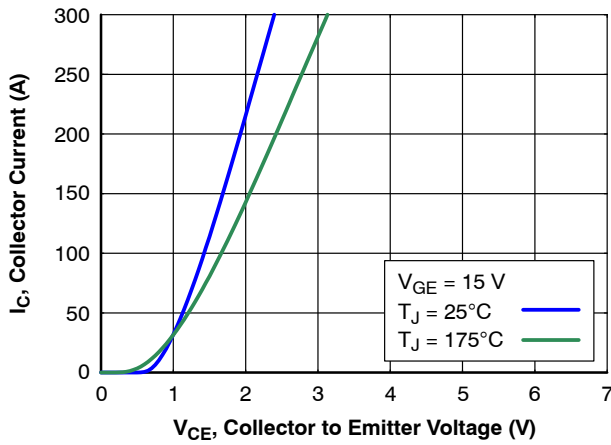


Figure 5. Saturation Voltage Characteristics

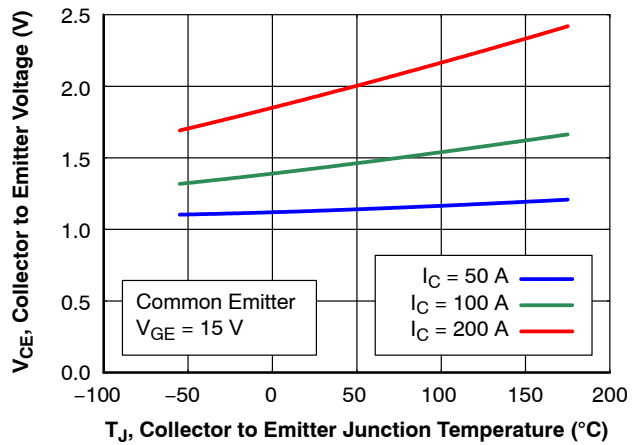


Figure 6. Saturation Voltage vs Junction Temperature

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TYPICAL CHARACTERISTICS (CONTINUED)

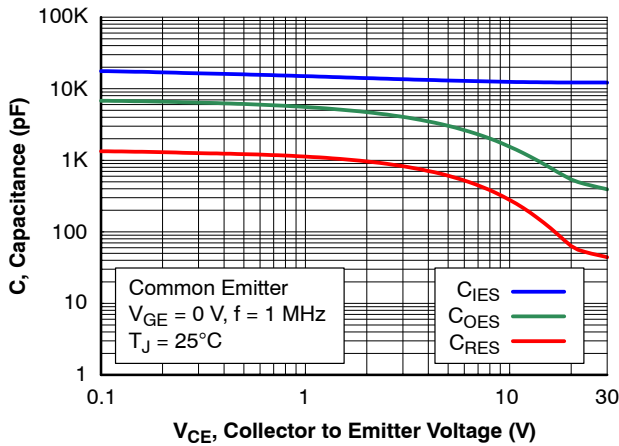


Figure 7. Capacitance Characteristics

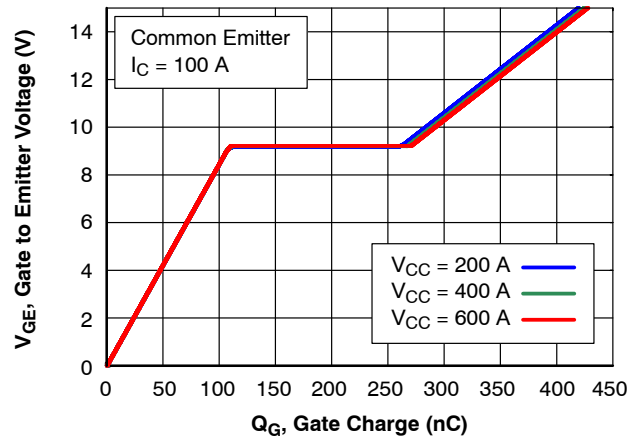


Figure 8. Gate Charge Characteristics

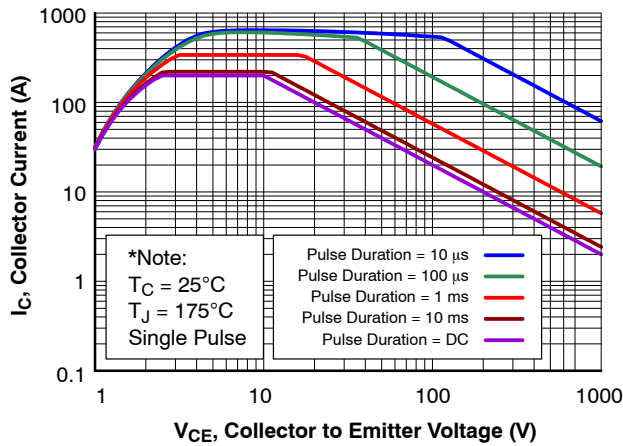


Figure 9. SOA Characteristics

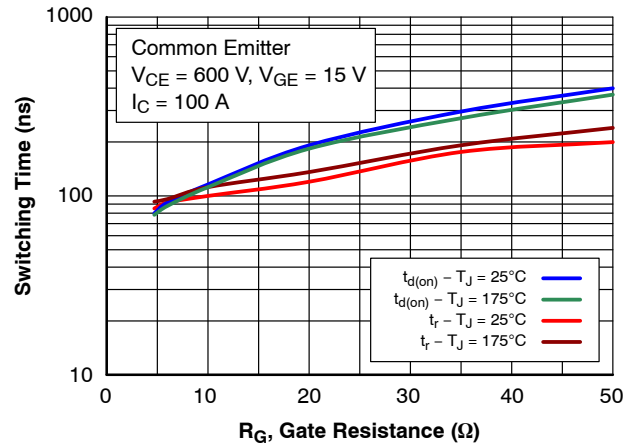


Figure 10. Turn-On Time vs Gate Resistance

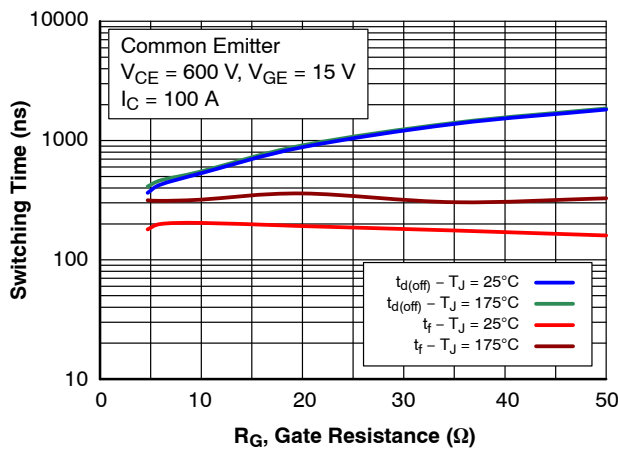


Figure 11. Turn-Off Time vs Gate Resistance

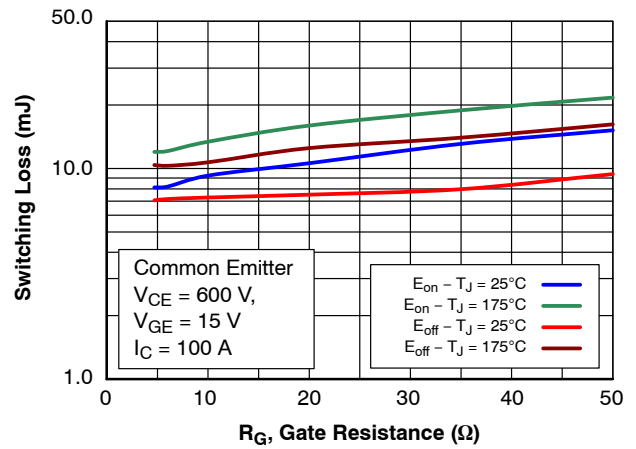


Figure 12. Switching Loss vs Gate Resistance

TYPICAL CHARACTERISTICS (CONTINUED)

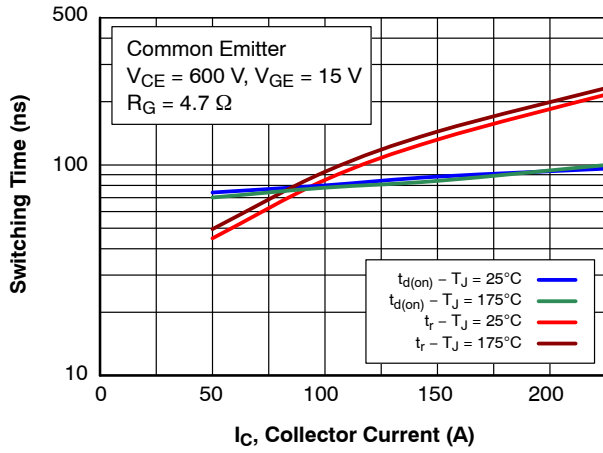


Figure 13. Turn-On Time vs Collector Current

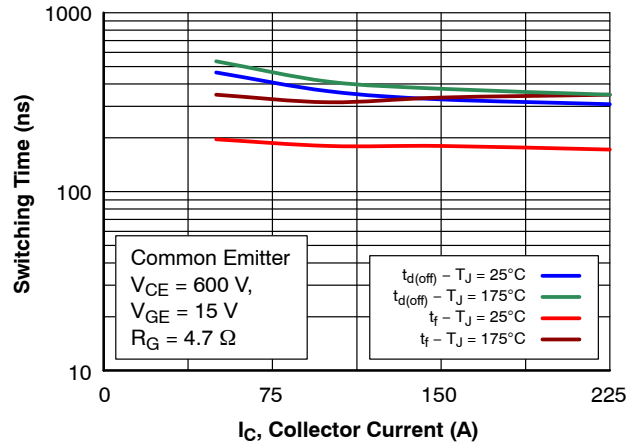


Figure 14. Turn-Off Time vs Collector Current

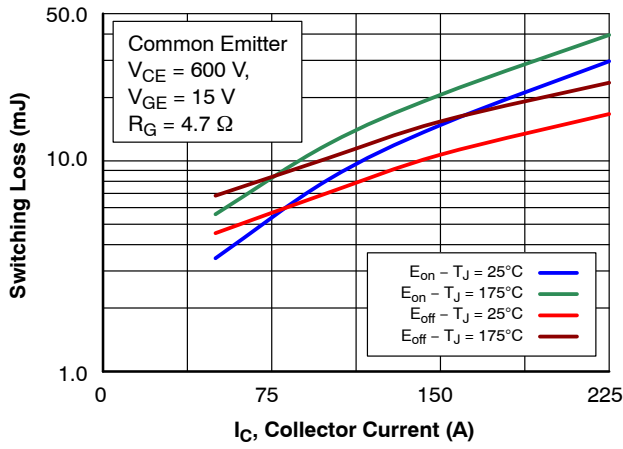


Figure 15. Switching Loss vs Collector Current

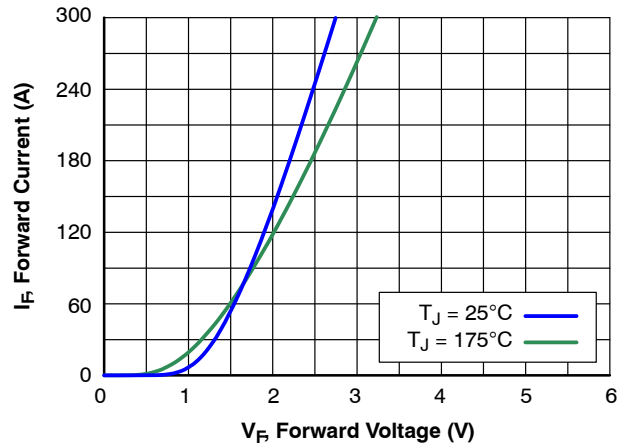


Figure 16. Diode Forward Characteristics

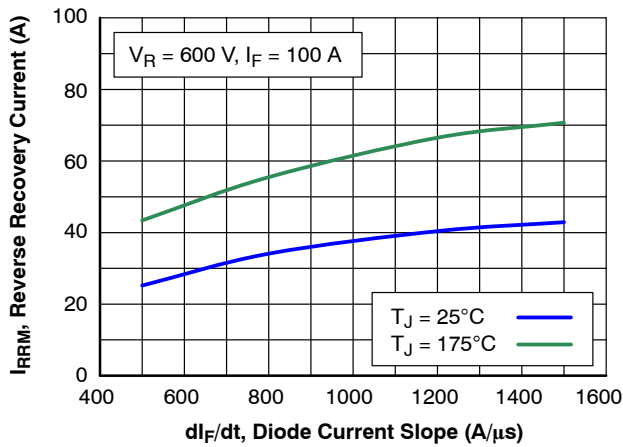


Figure 17. Diode Reverse Recovery Current

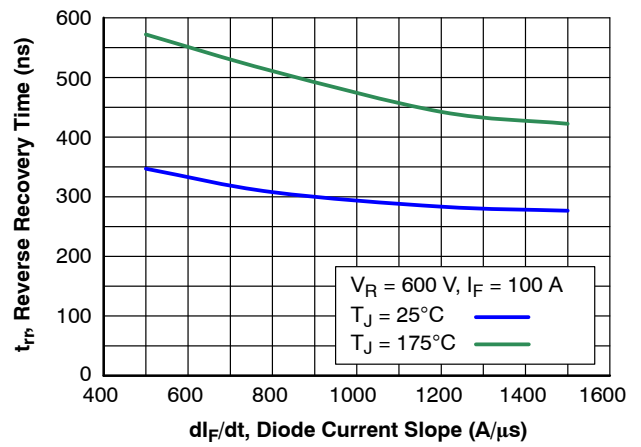


Figure 18. Diode Reverse Recovery Time

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TYPICAL CHARACTERISTICS (CONTINUED)

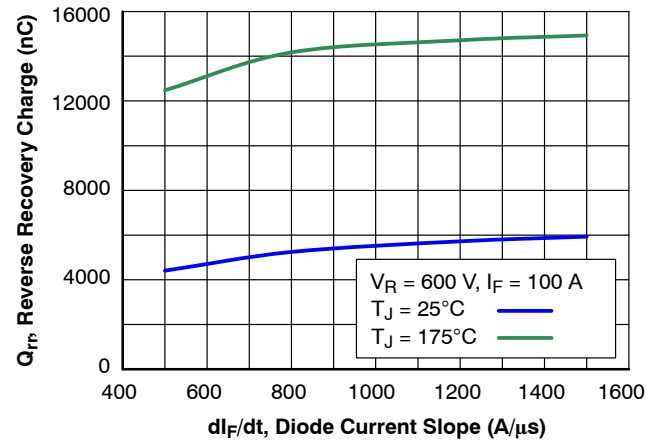


Figure 19. Diode Stored Charge Characteristics

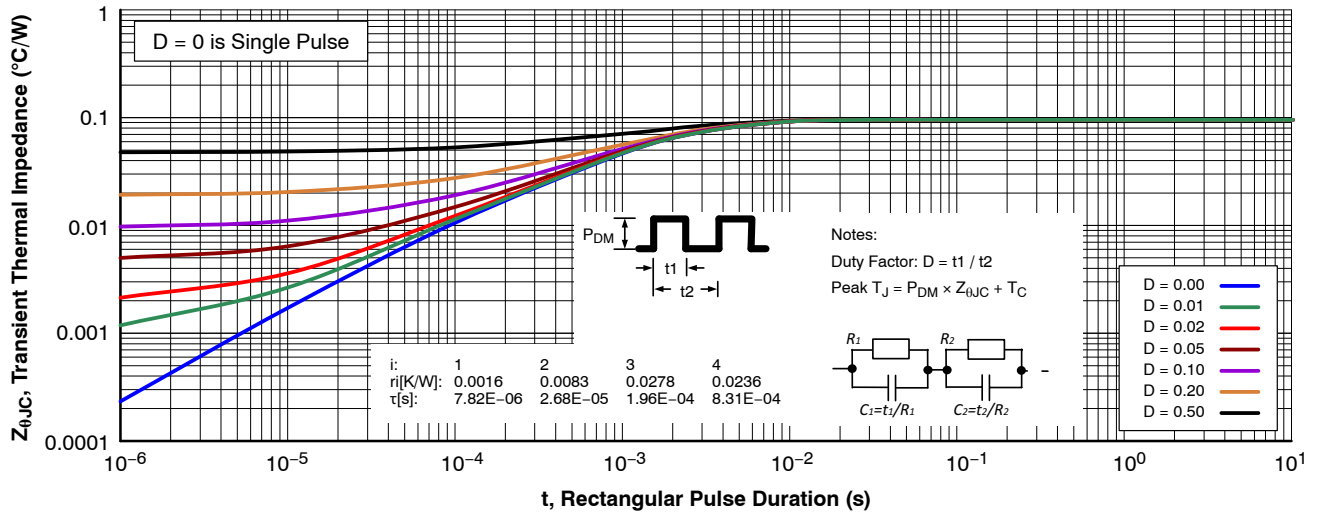


Figure 20. Transient Thermal Impedance of IGBT

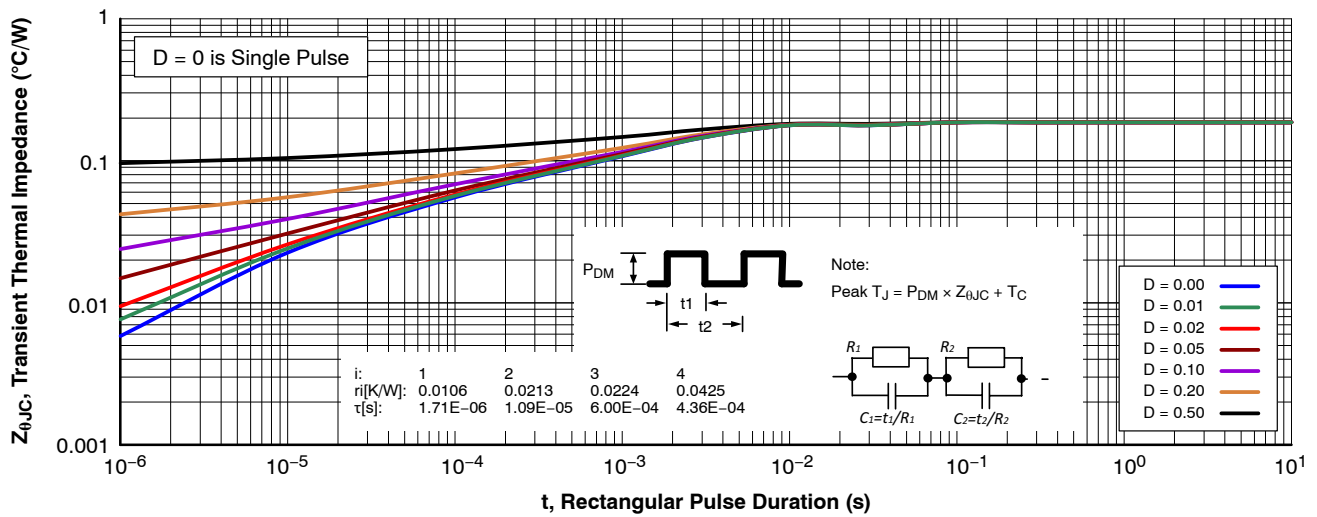
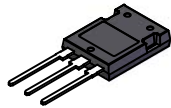


Figure 21. Transient Thermal Impedance of Diode

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

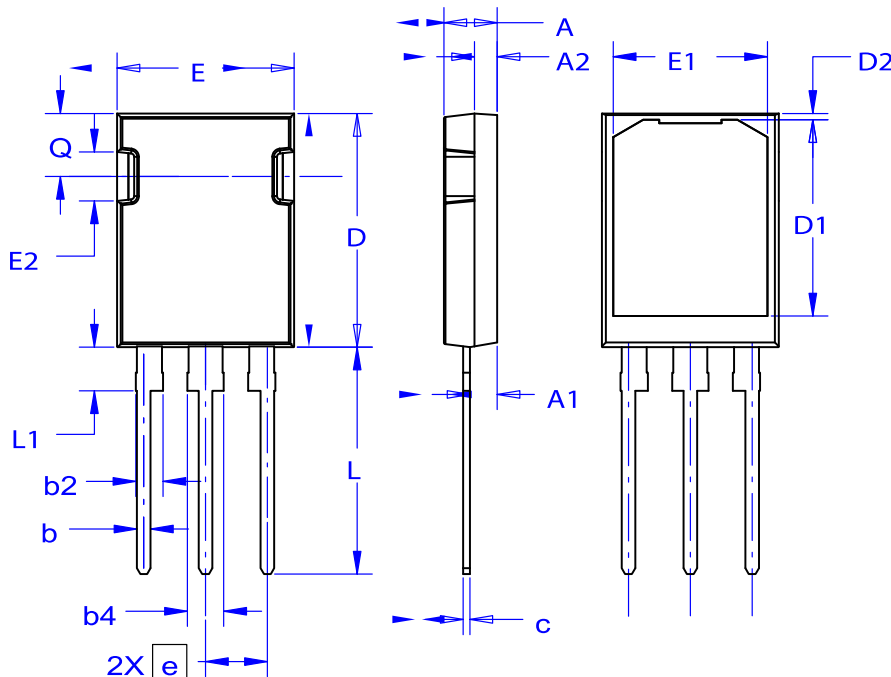


TO-247-3LD
CASE 340CD
ISSUE A

DATE 18 SEP 2018

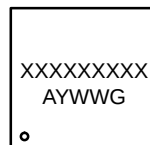
NOTES:

- A. THIS PACKAGE DOES NOT CONFORM TO ANY STANDARDS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.



DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.58	4.70	4.82
A1	2.20	2.40	2.60
A2	1.80	2.00	2.20
D	20.32	20.57	20.82
E	15.37	15.62	15.87
E2	4.12	4.32	4.52
e	~	5.45	~
L	19.90	20.00	20.10
L1	3.69	3.81	3.93
Q	5.34	5.46	5.58
b	1.10	1.20	1.30
b2	2.10	2.24	2.39
b4	2.87	3.04	3.20
c	0.51	0.61	0.71
D1	16.63	16.83	17.03
D2	0.51	0.93	1.35
E1	13.40	13.60	13.80

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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